

=> fil cap  
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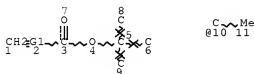
FILE COVERS 1907 - 4 Aug 2008 VOL 149 ISS 6  
 FILE LAST UPDATED: 3 Aug 2008 (20080803/ED)

Caplus now includes complete International Patent Classification (IPC) reclassification data for the second quarter of 2008.

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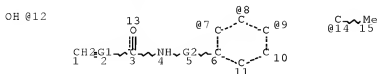
=> d que 116  
 L3 STR



VAR G1=CH/10  
 NODE ATTRIBUTES:  
 DEFAULT MLEVEL IS ATOM  
 DEFAULT ECLEVEL IS LIMITED

GRAPH ATTRIBUTES:  
 RING(S) ARE ISOLATED OR EMBEDDED  
 NUMBER OF NODES IS 11

STEREO ATTRIBUTES: NONE  
 L4 STR



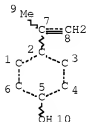
```

VAR G1=CH/14
REP G2=(0-4) CH2
VPA 12-7/8/9 U
NODE ATTRIBUTES:
DEFAULT MLEVEL IS ATOM
DEFAULT ELEVEL IS LIMITED

GRAPH ATTRIBUTES:
RING(S) ARE ISOLATED OR EMBEDDED
NUMBER OF NODES IS 15

STEREO ATTRIBUTES: NONE
L5          STR

```



```

NODE ATTRIBUTES:
DEFAULT MLEVEL IS ATOM
DEFAULT ELEVEL IS LIMITED

GRAPH ATTRIBUTES:
RING(S) ARE ISOLATED OR EMBEDDED
NUMBER OF NODES IS 10

STEREO ATTRIBUTES: NONE
L9          15663 SEA FILE=REGISTRY SSS FUL L3
L12         18 SEA FILE=REGISTRY SUB=L9 SSS FUL L4
L14         77 SEA FILE=REGISTRY SUB=L9 SSS FUL L5
L15         11 SEA FILE=REGISTRY ABB=ON PLU=ON L14 AND L12
L16         3 SEA FILE=CAPLUS ABB=ON PLU=ON L15

```

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=> d l16 ibib abs hitstr tot
```

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L16 ANSWER 1 OF 3 CAPLUS COPYRIGHT 2008 ACS on STN
ACCESSION NUMBER: 2006:1282746 CAPLUS Full-text
DOCUMENT NUMBER: 146:52382
TITLE: Positive-working radiation-sensitive resin composition
        containing vinyl alkyl ether resin, transfer film, and
        manufacture of plate molding
INVENTOR(S): Nishikawa, Koji; Mori, Kosuke; Ota, Suguru; Iwanaga,
        Shinichiro
PATENT ASSIGNEE(S): Jsr Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 26pp.
        CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

```

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2006330366	A	20061207	JP 2005-153985	20050526

PRIORITY APPLN. INFO.:  
 JP 2005-153985 20050526  
 JP 2005-153985 20050526

AB Disclosed is a pos.-working radiation-sensitive resin composition comprising a polymer releasing an acid group upon interaction with an acid, a vinyl alkyl ether resin represented by  $\text{CH}_2\text{R}_1\text{CH}_2\text{CH}_2[\text{CH}(\text{OR}_3)\text{CH}_2]_n\text{CH}_2\text{CH}_2\text{R}_2$  ( $\text{R}_1, 2 = \text{H}, \text{COOH}$ ;  $\text{R}_3 = \text{C}_1\text{-4 alkyl}$ ; and  $n = \text{integer } \geq 1$ ), a compound releasing an acid upon receiving radiation, and an organic solvent.

IT 316323-80-3P  
 RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)  
 (Pos.-working radiation-sensitive resin composition containing vinyl alkyl ether resin)

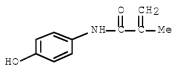
RN 916323-80-3 CAPLUS

CN 2-Propenoic acid, 1,1-dimethylethyl ester, polymer with 2-hydroxyethyl 2-propenoate, N-(4-hydroxyphenyl)-2-methyl-2-propenamide, 4-(1-methylethenyl)phenol and phenylmethyl 2-propenoate (CA INDEX NAME)

CM 1

CRN 19243-95-9

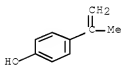
CMF C10 H11 N O2



CM 2

CRN 4286-23-1

CMF C9 H10 O



CM 3

CRN 2495-35-4

CMF C10 H10 O2



CM 4

CRN 1663-39-4

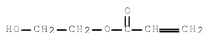
CMF C7 H12 O2



CM 5

CRN 818-61-1

CMF C5 H8 O3



L16 ANSWER 2 OF 3 CAPLUS COPYRIGHT 2008 ACS on STN

ACCESSION NUMBER: 2006:534488 CAPLUS Full-text

DOCUMENT NUMBER: 145:19039

TITLE: Radiation-sensitive resists, resist films and transfer films both made from same, and manufacture of electroplated electrically conductive metal structures by using patterned resists as templates

INVENTOR(S): Yokoyama, Kenichi; Nishikawa, Koji; Iwanaga, Shinichiro

PATENT ASSIGNEE(S): Jsr Ltd., Japan

SOURCE: Jpn. Kokai Tokkyo Koho, 44 pp.

CODEN: JKXXAF

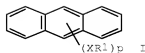
DOCUMENT TYPE: Patent

LANGUAGE: Japanese

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
-----	----	-----	-----	-----
JP 2006145853	A	20060608	JP 2004-336055	20041119
PRIORITY APPLN. INFO.:			JP 2004-336055	20041119
OTHER SOURCE(S):	MARPAT 145:19039			
GI				

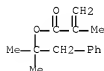


- AB The resists contain (A) 0.1-20 weight parts of anthracene derivs. I [p = 1-10; R<sup>1</sup> = H, C1-8 (substituted) alkyl, C3-20 (substituted) alicyclic group, C2-4 alkenyl, etc.; ≥2 of R<sup>1</sup> may form ring (containing hetero atoms); X = direct bond, O, S, CO, N(R'), etc.; R' = H, C1-8 (substituted) alkyl, C3-20 (substituted) alicyclic group, etc.; ≥2 of R' may form ring], (B) 0.1-20 weight parts of photoacid generators, and (C) 100 weight parts of polymers, and show sensitivity for 300-450 nm radiation. Also claimed are pos.-working above resists containing polymers bearing acid-labile groups as C. Also claimed are neg.-working above resists containing alkali-soluble polymers as C, and crosslinking agents capable of reaction with the alkali-soluble polymers under the presence of acids. In manufacture of elec. conductive metal structures (e.g., bumps and wirings of circuits), electroplating of the metal is carried out on patterned resists used as templates. The resists, sensitive for both i-line and g-line, provide patterns with good profile.
- IT 887704-12-3P, 2-Benzyl-2-propyl methacrylate-2-hydroxyethyl acrylate-p-hydroxyphenyl methacrylamide-isobornyl acrylate-α-methyl-4-hydroxystyrene copolymer 887704-13-4P 887704-14-5P  
 RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)  
 (pos. resist component; UV resists containing anthracene sensitizers, transfer films, and electroplating of conductor metals on patterned resists)
- RN 887704-12-3 CAPLUS
- CN 2-Propenoic acid, 2-methyl-, 1,1-dimethyl-2-phenylethyl ester, polymer with 2-hydroxyethyl 2-propenoate, N-(4-hydroxyphenyl)-2-methyl-2-propenamide, 4-(1-methylethenyl)phenol and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 887704-11-2

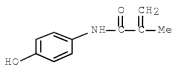
CMF C14 H18 O2



CM 2

CRN 19243-95-9

CMF C10 H11 N O2

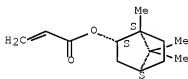


CM 3

CRN 5888-33-5

CMF C13 H20 O2

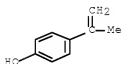
Relative stereochemistry.



CM 4

CRN 4286-23-1

CMF C9 H10 O



CM 5

CRN 818-61-1

CMF C5 H8 O3



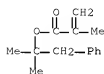
RN 887704-13-4 CAPLUS

CN 2-Propenoic acid, 2-methyl-, 1,1-dimethyl-2-phenylethyl ester, polymer with 2-hydroxyethyl 2-propenoate, N-(4-hydroxyphenyl)-2-methyl-2-propenamide and 4-(1-methylethenyl)phenol (9CI) (CA INDEX NAME)

CM 1

CRN 887704-11-2

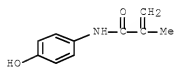
CMF C14 H18 O2



CM 2

CRN 19243-95-9

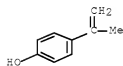
CMF C10 H11 N O2



CM 3

CRN 4286-23-1

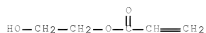
CMF C9 H10 O



CM 4

CRN 818-61-1

CMF C5 H8 O3



RN 887704-14-5 CAPLUS

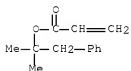
CN 2-Propenoic acid, 1,1-dimethyl-2-phenylethyl ester, polymer with

2-hydroxyethyl 2-propenoate, N-(4-hydroxyphenyl)-2-methyl-2-propenamide  
and 4-(1-methylethenyl)phenol (9CI) (CA INDEX NAME)

CM 1

CRN 324767-19-3

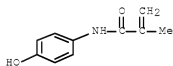
CMF C13 H16 O2



CM 2

CRN 19243-95-9

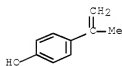
CMF C10 H11 N O2



CM 3

CRN 4286-23-1

CMF C9 H10 O



CM 4

CRN 818-61-1

CMF C5 H8 O3

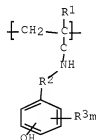




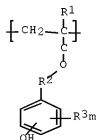
L16 ANSWER 3 OF 3 CAPLUS COPYRIGHT 2008 ACS on STN  
 ACCESSION NUMBER: 2005:1049905 CAPLUS Full-text  
 DOCUMENT NUMBER: 143:356609  
 TITLE: Positively radiation-sensitive resin composition  
 INVENTOR(S): Nishikawa, Kouji; Iwanaga, Shinichiro  
 PATENT ASSIGNEE(S): JSR Corporation, Japan  
 SOURCE: PCT Int. Appl., 46 pp.  
 CODEN: PIXXD2  
 DOCUMENT TYPE: Patent  
 LANGUAGE: Japanese  
 FAMILY ACC. NUM. COUNT: 1  
 PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
WO 2005091074	A1	20050929	WO 2005-JP5398	20050324
W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW RW: BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG				
EP 1729176	A1	20061206	EP 2005-721412	20050324
R: DE, FR, IT				
CN 1934499	A	20070321	CN 2005-80009064	20050324
US 20070190465	A1	20070816	US 2006-593812	20060922
KR 20070071152	A	20070112	KR 2006-721970	20061023
PRIORITY APPLN. INFO.:			JP 2004-87520	A 20040324
			WO 2005-JP5398	W 20050324

GI



I



II

AB A production process by which thick deposits, such as bumps or wirings, can be formed by plating with satisfactory precision; a pos. radiation-sensitive resin composition which is suitable for use in the production process and is

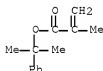
excellent in sensitivity, resolution, etc.; and a transfer film comprising the composition. The pos. radiation-sensitive resin composition comprises (A) a polymer having structural units (a) represented by the following general formula I and/or II (R1 = H, methyl; R2 = -(CH2)n-; n = integer 0-30; R3 = C1-4 alkyl; m = 0-4 integer) and an acid-dissociable functional group (b), (B) an ingredient which generates an acid upon irradiation with a radiation, and (C) an organic solvent. A pos. radiation-sensitive resin film comprising the composition can also be produced.

- IT 865783-70-6P, N-(p-Hydroxyphenyl)methacrylamide-p-Isopropenylphenol-2-Hydroxyethyl acrylate-Isobornyl acrylate-2-Phenyl-2-propyl methacrylate copolymer 865783-71-7P, N-(p-Hydroxyphenyl)methacrylamide-p-Isopropenylphenol-2-Hydroxyethyl acrylate-2-Phenyl-2-propyl methacrylate copolymer 865783-72-6P, N-(p-Hydroxyphenyl)methacrylamide-p-Isopropenylphenol-2-Hydroxyethyl acrylate-2-Propenoic acid, 1-methyl-1-phenylethyl ester copolymer 865783-78-4P, N-(p-Hydroxyphenyl)methacrylamide-p-Isopropenylphenol-benzyl acrylate-tert-butyl acrylate copolymer 865783-79-5P, N-(p-Hydroxyphenyl)methacrylamide-p-Isopropenylphenol-Isobornyl acrylate-tert-butyl acrylate copolymer 865783-80-8P, N-(p-Hydroxyphenyl)methacrylamide-p-Isopropenylphenol-benzyl acrylate-tert-butyl methacrylate copolymer 865783-81-9P, N-(p-Hydroxyphenyl)methacrylamide-p-Isopropenylphenol-1-methyl-1-phenylethyl 2-propenoate copolymer  
 RL: SPN (Synthetic preparation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)  
 (invention's resin in pos. radiation-sensitive resin composition)
- RN 865783-70-6 CAPLUS
- CN 2-Propenoic acid, 2-methyl-, 1-methyl-1-phenylethyl ester, polymer with 2-hydroxyethyl 2-propenoate, N-(4-hydroxyphenyl)-2-methyl-2-propenamide, 4-(1-methylethenyl)phenol and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 54554-17-5

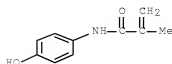
CMF C13 H16 O2



CM 2

CRN 19243-95-9

CMF C10 H11 N O2

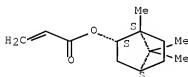


CM 3

CRN 5888-33-5

CMF C13 H20 O2

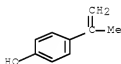
Relative stereochemistry.



CM 4

CRN 4286-23-1

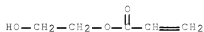
CMF C9 H10 O



CM 5

CRN 818-61-1

CMF C5 H8 O3



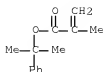
RN 865783-71-7 CAPLUS

CN 2-Propenoic acid, 2-methyl-, 1-methyl-1-phenylethyl ester, polymer with  
 2-hydroxyethyl 2-propenoate, N-(4-hydroxyphenyl)-2-methyl-2-propenamide  
 and 4-(1-methylethenyl)phenol (9CI) (CA INDEX NAME)

CM 1

CRN 54554-17-5

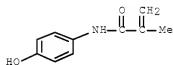
CMF C13 H16 O2



CM 2

CRN 19243-95-9

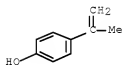
CMF C10 H11 N O2



CM 3

CRN 4286-23-1

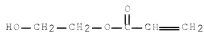
CMF C9 H10 O



CM 4

CRN 818-61-1

CMF C5 H8 O3

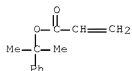


RN 865783-72-8 CAPLUS

CN 2-Propenoic acid, 2-hydroxyethyl ester, polymer with N-(4-hydroxyphenyl)-2-methyl-2-propenamide, 4-(1-methylethenyl)phenol and 1-methyl-1-phenylethyl 2-propenoate (9CI) (CA INDEX NAME)

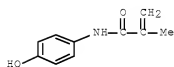
CM 1

CRN 67704-03-4  
CMF C12 H14 O2



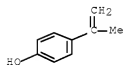
CM 2

CRN 19243-95-9  
CMF C10 H11 N O2



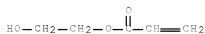
CM 3

CRN 4286-23-1  
CMF C9 H10 O



CM 4

CRN 818-61-1  
CMF C5 H8 O3



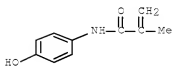
RN 865783-78-4 CAPLUS  
CN 2-Propenoic acid, 1,1-dimethylethyl ester, polymer with  
N-(4-hydroxyphenyl)-2-methyl-2-propenamide, 4-(1-methylethenyl)phenol and

phenylmethyl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 19243-95-9

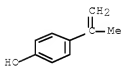
CMF C10 H11 N O2



CM 2

CRN 4286-23-1

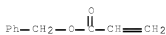
CMF C9 H10 O



CM 3

CRN 2495-35-4

CMF C10 H10 O2



CM 4

CRN 1663-39-4

CMF C7 H12 O2



RN 865783-79-5 CAPLUS

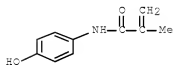
CN 2-Propenoic acid, 1,1-dimethylethyl ester, polymer with

N-(4-hydroxyphenyl)-2-methyl-2-propenamide, 4-(1-methylethenyl)phenol and  
 rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI)  
 (CA INDEX NAME)

CM 1

CRN 19243-95-9

CMF C10 H11 N O2

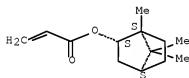


CM 2

CRN 5888-33-5

CMF C13 H20 O2

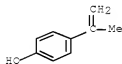
Relative stereochemistry.



CM 3

CRN 4286-23-1

CMF C9 H10 O



CM 4

CRN 1663-39-4

CMF C7 H12 O2



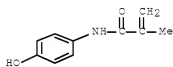
RN 865783-80-8 CAPLUS

CN 2-Propenoic acid, 2-methyl-, 1,1-dimethylethyl ester, polymer with  
N-(4-hydroxyphenyl)-2-methyl-2-propenamide, 4-(1-methylethenyl)phenol and  
phenylmethyl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 19243-95-9

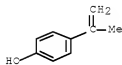
CMF C10 H11 N O2



CM 2

CRN 4286-23-1

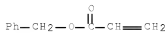
CMF C9 H10 O



CM 3

CRN 2495-35-4

CMF C10 H10 O2



CM 4

CRN 585-07-9

CMF C8 H14 O2



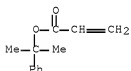


RN 865783-81-9 CAPLUS  
 CN 2-Propenoic acid, 1-methyl-1-phenylethyl ester, polymer with  
 N-(4-hydroxyphenyl)-2-methyl-2-propenamide and 4-(1-methylethenyl)phenol  
 (9CI) (CA INDEX NAME)

CM 1

CRN 67704-03-4

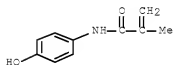
CMF C12 H14 O2



CM 2

CRN 19243-95-9

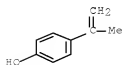
CMF C10 H11 N O2



CM 3

CRN 4286-23-1

CMF C9 H10 O



REFERENCE COUNT:

2

THERE ARE 2 CITED REFERENCES AVAILABLE FOR THIS  
 RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d his nofil

(FILE 'HOME' ENTERED AT 16:49:38 ON 04 AUG 2008)

FILE 'CAPLUS' ENTERED AT 16:49:47 ON 04 AUG 2008  
E US2006-593812/APPS

L1 1 SEA ABB=ON PLU=ON US2006-593812/AP  
SEL RN

FILE 'REGISTRY' ENTERED AT 16:50:07 ON 04 AUG 2008

L2 12 SEA ABB=ON PLU=ON (865783-70-6/BI OR 865783-71-7/BI OR  
865783-72-8/BI OR 865783-73-9/BI OR 865783-74-0/BI OR 865783-75  
-1/BI OR 865783-76-2/BI OR 865783-77-3/BI OR 865783-78-4/BI OR  
865783-79-5/BI OR 865783-80-8/BI OR 865783-81-9/BI)

L\*\*\* DEL

STR

L3

STR

D QUE L\*\*\*

L4

STR L\*\*\*

L5

STR

L6

50 SEA SSS SAM L3

L7

1 SEA SSS SAM L4

L8

0 SEA SSS SAM L5

L9

15663 SEA SSS FUL L3

FILE 'CAPLUS' ENTERED AT 16:56:17 ON 04 AUG 2008

L10 11243 SEA ABB=ON PLU=ON L9

FILE 'REGISTRY' ENTERED AT 16:56:25 ON 04 AUG 2008

L11 0 SEA SUB=L9 SSS SAM L4

L12 18 SEA SUB=L9 SSS FUL L4

L13 3 SEA SUB=L9 SSS SAM L5

L14 77 SEA SUB=L9 SSS FUL L5

L15 11 SEA ABB=ON PLU=ON L14 AND L12

FILE 'CAPLUS' ENTERED AT 16:57:42 ON 04 AUG 2008

L16 3 SEA ABB=ON PLU=ON L15

FILE 'REGISTRY' ENTERED AT 16:58:21 ON 04 AUG 2008

L\*\*\* DEL 0 S L15 AND RELATED POLYMERS/FA

L17 11 POLYLINK L15

FILE 'CAPLUS' ENTERED AT 16:59:01 ON 04 AUG 2008

D QUE L16

D L16 IBIB ABS HITSTR TOT